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Preface: International Conference on Inventive Material Science Applications (ICIMA2019) **FREE**


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
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Preface: International Conference on Inventive Material Science Applications (ICIMA2019)

This Conference Proceedings volume contains the written versions of most of the contributions presented during the conference of ICIMA 2019. The Conference provided a setting for discussing recent developments in a wide variety of topics including Metallurgy and Materials, Powder Metallurgy, Forming & Machining, Advanced Ceramics, Nanotechnology in Materials Science and Biomaterials.

The Conference has been a good opportunity for participants coming from various destinations to present and discuss topics in their respective research areas. The goal of this conference is to provide a platform for engineers and academicians all over the world to promote, share, and discuss various new issues and developments in different areas of Material Science and applications. It includes a selection of 29 papers from 92 papers submitted to the conference from universities and industries all over the world. All of accepted papers were subjected to strict peer-reviewing by 2-4 expert referees. The papers have been selected for this volume because of quality and the relevance to the conference

ICIMA 2019 would like to express our sincere appreciation to all authors for their contributions to this book. We would like to extend our thanks to all the referees for their constructive comments on all papers, especially, we would like to thank to organizing committee for their hard working. Finally, we would like to thank the AIP Publishing for producing this volume.

Dr. V. Bindhu
Conference Chair
ICIMA 2019